

# 次世代PKG基板用の 高信頼性穴埋めインキ!

High-Reliability Hole Plugging Ink for PKG Substrate of Next Generation



## 熱硬化型穴埋めインキ THP-100DX Series

High-Reliability Hole Plugging Ink for PKG Substrate of Next Generation

### 特長 Features

#### ■ 高Tg/低CTE

High Tg/Low CTE

#### ■ TCT耐性良好

Excellent anti crack resistance at TCT  
-65°C⇔150°C/1000cycle/No crack

#### ■ リフロー耐性良好

Excellent anti crack resistance at reflow

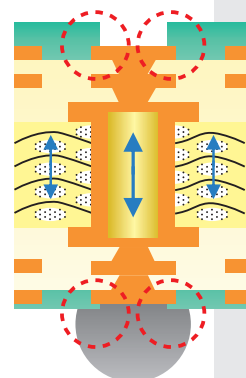
### 特性 Properties

|                       | 従来品<br>Conventional product | THP-100 DX7<br>Mass-produced | THP-100 DX9<br>Development Product | Test Condition                            |
|-----------------------|-----------------------------|------------------------------|------------------------------------|-------------------------------------------|
| 粘度 (dPa·s)            | 450±50                      | 450±50                       | 450±50                             | コーンプレート型粘度計<br>Cone plate type viscometer |
| ガラス転移温度(deg.C) Tg     | 150-160                     | 165-175                      | 175-185                            | TMA (Pulling mode)<br>X-Y方向 X-Y direction |
| 線膨張係数(ppm) CTE(α1/α2) | 30-35/100-110               | 20-25/55-65                  | 10-15/35-45                        |                                           |

|                                                     | 従来品<br>Conventional product | THP-100 DX7 |
|-----------------------------------------------------|-----------------------------|-------------|
| Before Reflow                                       |                             |             |
| L2a<br>(C-120/60/60)<br>+ Reflow<br>(270°C/5cycles) |                             |             |

- ① Core T=0.4mm PTH=0.25mm
- ② Treatment  
L2a(C120/60/60)  
+Reflow(270°C/5cycles)

※基板表面実温度



### 用途 Application

■ THP-100 DX7: 現行PKG、通信、車載基板

■ THP-100 DX9: 次世代PKG基板